



Atty. Dkt. No. AMAT/3577.X1/DSM/BCVD/JW

PATENT

AF/1700  
16D  
BH  
1/6/03  
(DE)

In re Application of:  
Huang

Serial No.: 09/336,525

Confirmation No.: 7748

Filed: June 18, 1999

For: Plasma Treatment to Enhance  
Adhesion and to Minimize  
Oxidation of Carbon-Containing  
Layers

Group Art Unit: 1762

Examiner: Padgett, M.

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Commissioner for Patents  
Washington, D.C. 20231

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I hereby certify that this correspondence is being deposited on <u>12/17/02</u> with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.	
<u>12/17/02</u> Date	<u>Kim [Signature]</u> Signature

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Dear Sir:

### RESPONSE TO FINAL OFFICE ACTION DATED NOVEMBER 5, 2002

In response to the Final Office Action dated November 5, 2002, having a shortened statutory period for response set to expire on February 5, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below.

### IN THE CLAIMS:

Please cancel claims 46-47 and 49, without prejudice. For the Examiner's convenience, all pending claims as set forth below and amendments are proposed as noted below.

24. (Amended) A method of processing a semiconductor substrate, comprising: